# **4 Channel EMI Pi-Filter Array with Full USB Filter**

This device is a 4 channel EMI filter array for data lines. Greater than -35 dB attenuation is obtained at frequencies from 800 MHz to 2.2 GHz. It also offers USB filtering circuitry with speed detection. This includes the inline resistors for impedance matching and EMI filtering. ESD protection is provided across all capacitors.

#### **Features**

- EMI Filtering and ESD Protection for Data Lines
- USB 1.1 Filtering Provided with Speed Detection
- Integration of 27 Discretes Offers Cost and Space Savings
- Pb-Free Package May be Available. The G-Suffix Denotes a Pb-Free Lead Finish
- 350 µm Solder Spheres
- All TVS Protected Inputs Comply with IEC61000–4–2 (Level 4) 30 kV (Contact) 30 kV (Air)
- Low Profile Flip-Chip Packaging
- All Pins Exceed 2000 Volts Human Body Model

#### **Typical Applications**

- EMI and USB Filtering and ESD Protection for Data Lines
- Cell Phones
- Handheld Portables
- Notebook Computers
- MP3 Players

#### **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
ESD Discharge IEC61000–4–2 (Note 1) – Air Discharge, Contact Discharge Human Body Model Machine Model	V <sub>PP</sub>	30 16 0.4	kV
DC Power per Resistor	P <sub>R</sub>	100	mW
DC Power per Package	P <sub>T</sub>	600	mW
Junction Temperature	TJ	150	°C
Operating Temperature Range	T <sub>op</sub>	-40 to +85	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C

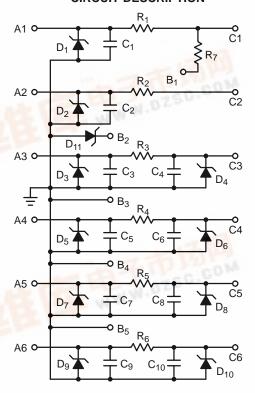
<sup>1.</sup> This does not include Pins B1, C1 and C2



#### ON Semiconductor®

http://onsemi.com

#### **CIRCUIT DESCRIPTION**





FLIP-CHIP-17 CASE 499AD

#### **DEVICE MARKING**



#### ORDERING INFORMATION

Device	Package	Shipping†
NUF4107FCT1G	Flip-Chip	3000/Tape & Reel

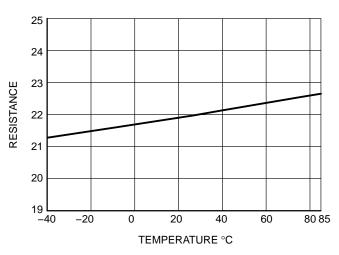
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Characteristic	Min	Тур	Max	Unit
V <sub>BR</sub>	I <sub>R</sub> = 1 mA	6.0	6.8	8.0	V
I <sub>R</sub>	V <sub>RM</sub> = 3.3 V per line	-	-	0.1	μΑ
R <sub>3</sub> – R <sub>6</sub>	EMI Filter Resistors	80	100	120	Ω
R <sub>1</sub> , R <sub>2</sub>	USB Resistors; Impedance Matching	18	22	26	Ω
R <sub>7</sub>	USB Pull-up; Speed Detection Resistor	1250	1500	1750	Ω
C <sub>line</sub>	At 2.5 V Bias	48	60	72	pF
C1, C2	At Pins A1 and A2; At 2.5 V Bias	29	36	43	pF
C <sub>power</sub>	At Pins B2; At 2.5 V Bias	54	68	82	pF

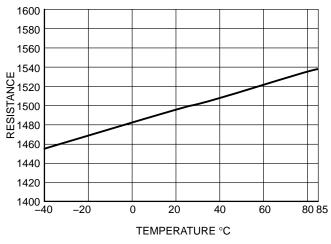
#### **TYPICAL CHARACTERISTICS**



110 108 106 104 RESISTANCE 102 100 98 96 94 92 90 -40 -20 20 40 60 80 85 0 TEMPERATURE °C

Figure 1. USB 1.1 Resistors (R1, R2) vs. Temperature

Figure 2. Data Resistors (R3, R4, R5, R6) vs. Temperature



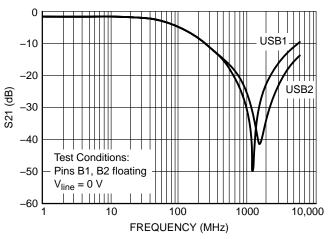
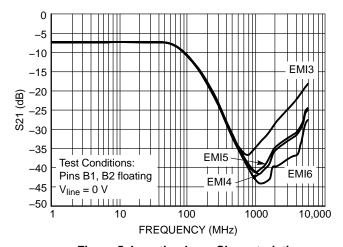


Figure 3. Pull-up Resistor (R7) vs. Temperature

Figure 4. Insertion Loss Characteristic USB1, USB2



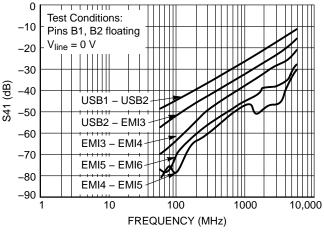


Figure 5. Insertion Loss Characteristic EMI3, EMI4, EMI5, EMI6

Figure 6. Analog Crosstalk Curve EMI Filter

#### **Printed Circuit Board Recommendations**

Parameter	500 μm Pitch 300 μm Solder Ball	
PCB Pad Size	250 μm +25 -0	
Pad Shape	Round	
Pad Type	NSMD	
Solder Mask Opening	350 μm ±25	
Solder Stencil Thickness	125 μm	
Stencil Aperture	250 x 250 μm sq.	
Solder Flux Ratio	50/50	
Solder Paste Type	No Clean Type 3 or Finer	
Trace Finish	OSP Cu	
Trace Width	150 μm Max	

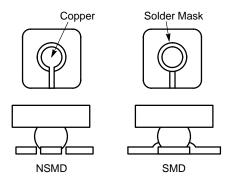


Figure 7. Solder Mask versus Non-Solder Mask Definition

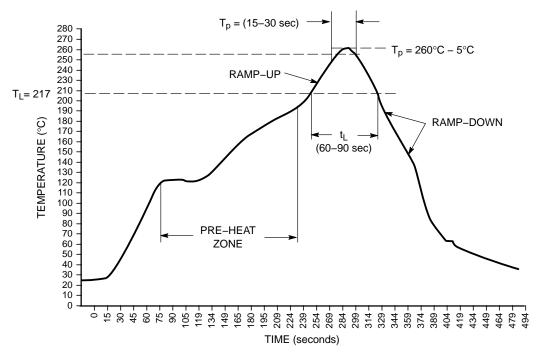
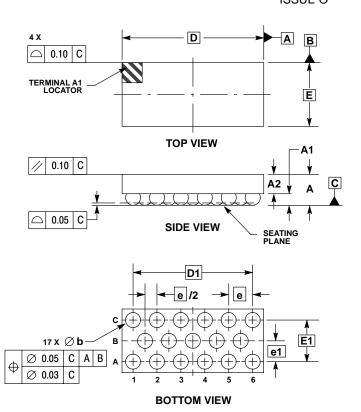


Figure 8. Typical Pb-Free Solder Heating Profile

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#### **PACKAGE DIMENSIONS**

#### FLIP-CHIP-17 CSP CASE 499AD-01 ISSUE O



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.740	
A1	0.250	0.310	
A2	0.380	0.430	
D	2.960 BSC		
E	1.330 BSC		
b	0.290	0.350	
е	0.500 BSC		
e1	0.435 BSC		
D1	2.500	BSC	
E1	0.870 BSC		

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